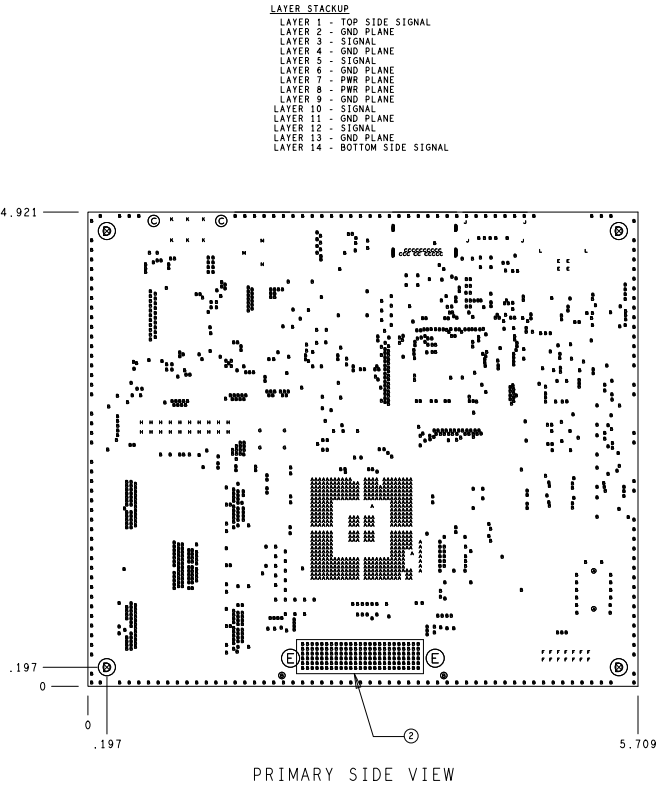


DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATING	QTY
A	9.0	+3.0/-3.0	PLATED	509
B	12.0	+3.0/-12.0	PLATED	1338
C	15.748	+1.969/-1.969	PLATED	20
D	23.622	+3.0/-3.0	PLATED	28
E	36.0	+3.0/-3.0	PLATED	4
F	38.0	+3.0/-3.0	PLATED	14
G	40.0	+3.0/-3.0	PLATED	4
H	42.0	+3.0/-3.0	PLATED	20
J	52.0	+3.0/-3.0	PLATED	4
K	55.0	+3.0/-3.0	PLATED	6
L	90.0	+3.0/-3.0	PLATED	2
M	120.0	+3.0/-3.0	PLATED	2
N	140.0	+3.0/-3.0	PLATED	1
Ⓐ	40.0	+3.0/-3.0	NON-PLATED	2
Ⓑ	66.0	+3.0/-3.0	NON-PLATED	2
Ⓒ	118.0	+3.0/-3.0	NON-PLATED	2
Ⓓ	180.0	+3.0/-3.0	NON-PLATED	4
Ⓔ	182.0	+3.0/-3.0	NON-PLATED	2

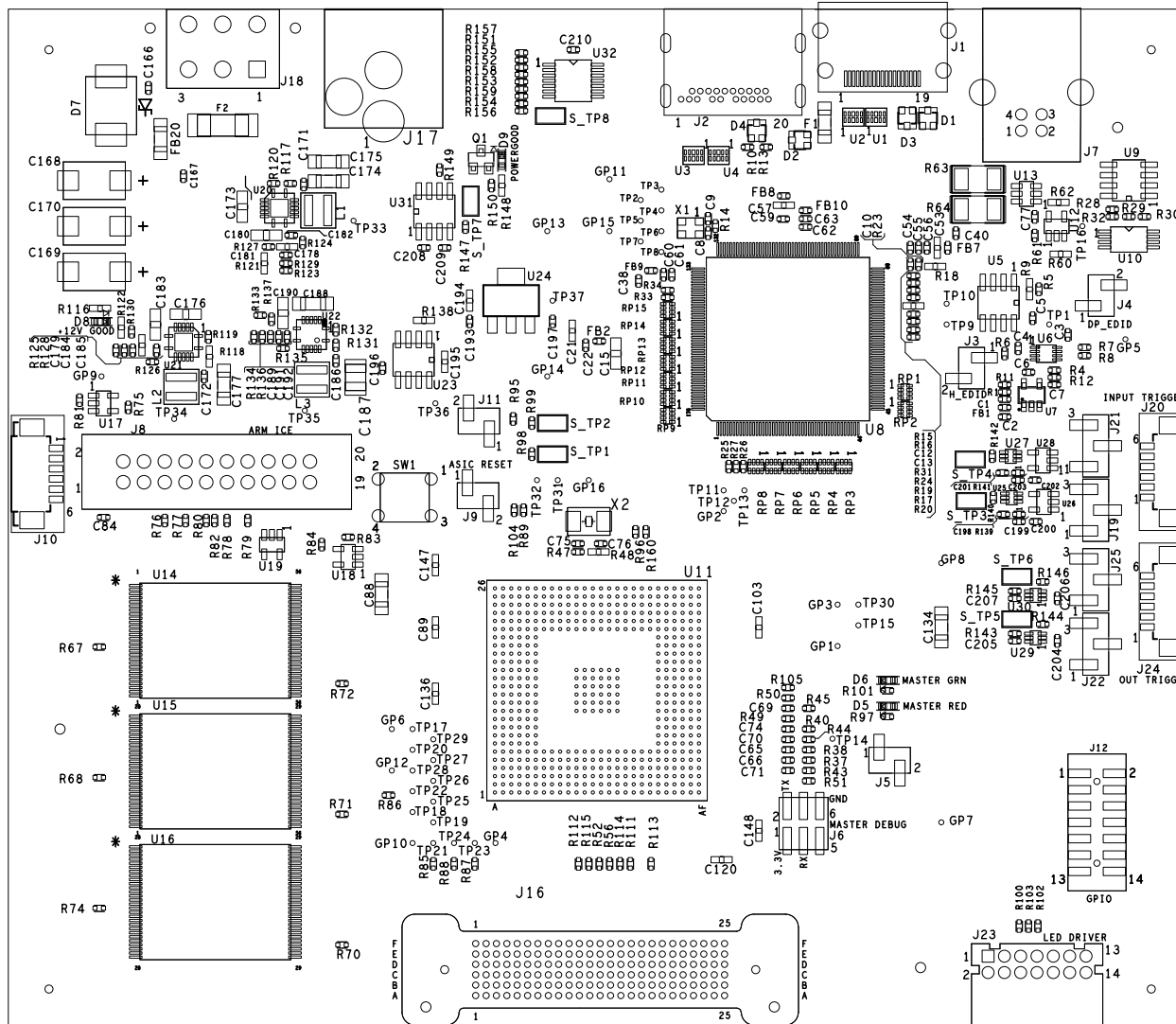


- FAB NOTES:
1. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010".
 2. THE PWB SHALL BE FABRICATED TO IPC-6012 CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
 3. BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT. ROHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B ROHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
 4. BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD.
 5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH. WITH A MINIMUM ANNUAL RING OF .002 INCH.
 6. OVERALL BOARD THICKNESS TO BE .079 +/- .01X AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. MEASURED FROM COPPER TO COPPER.
 7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
 8. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
 9. ALL LAYERS TO BE 1/2 OZ STARTING COPPER WEIGHT.
 10. FABRICATOR SHALL REMOVE ANY UNUSED PADS ON INTERNAL LAYERS.
 11. TRACE WIDTHS WITH NO SPECIFIED IMPEDANCE REQUIREMENTS SHOULD BE BUILT TO INDICATED WIDTH.

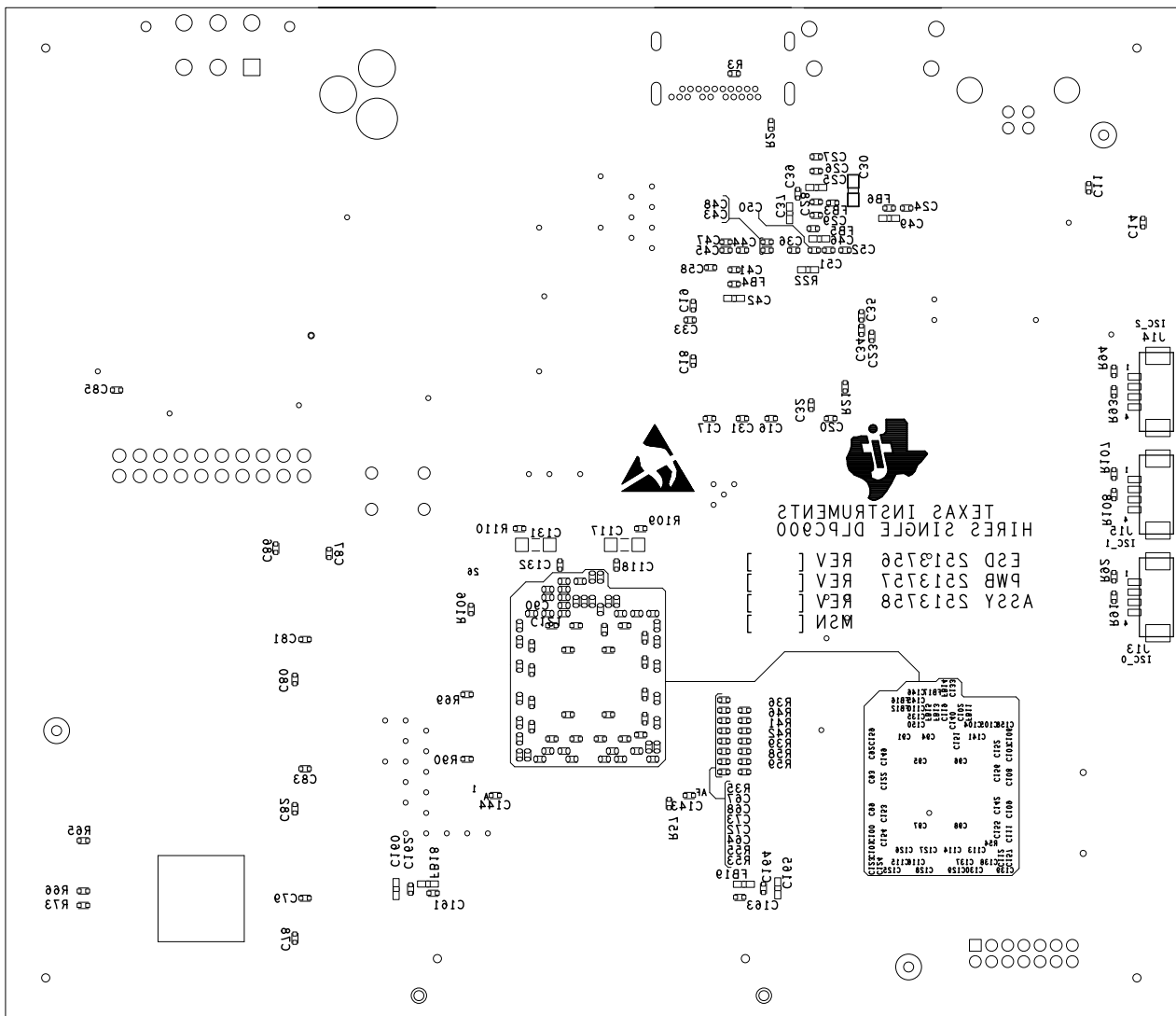
- PROCESS NOTES:
1. EXCEPT AS NOTED, PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD. FLASH GOLD PROCESS IS ALSO ACCEPTABLE. REQUIRED PLATING THICKNESS: NICKEL 150 MICROINCH MIN. GOLD 5-15 MICROINCHES THK.
 2. PLATE INDICATED AREAS (TOP SIDE) WITH ELECTROPLATED GOLD (35-50 MICROINCHES) OVER ELECTROPLATED NICKEL (MINIMUM 100 MICROINCHES).
 3. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC). COLOR: GREEN. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H, CURRENT REV.
 4. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATOR VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
 5. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.

CONTROLLED IMPEDANCE DESIGN	
6.8 MIL TRACES ON EXTERNAL LAYERS SHALL BE 50 OHMS SINGLE ENDED	
5.7 MIL TRACES ON INTERNAL LAYERS SHALL BE 50 OHMS SINGLE ENDED	
5.5 MIL TRACES WITH 5.5 MIL SPACES ON EXTERNAL LAYERS SHALL BE 90 OHMS DIFFERENTIAL	
5.4 MIL TRACES WITH 5.6 MIL SPACES ON INTERNAL LAYERS SHALL BE 90 OHMS DIFFERENTIAL	
4.75 MIL TRACES WITH 7.25 MIL SPACES ON ALL LAYERS SHALL BE 100 OHMS DIFFERENTIAL	

CUSTOMER NAME		TEXAS INSTRUMENTS	
BOARD NAME	DESCRIPTION		DRILL DRAWING
H1RES SINGLE DLPC900			
BOARD NO.	REV	DATE	SH 14 OF 14
2513757	B	16 AUG 2014	



CUSTOMER NAME		TEXAS INSTRUMENTS		ASSEMBLY TOP 1 of 2	
BOARD NAME		HIRES SINGLE DLPC900		DESCRIPTION	
				Silkscreen - Top Side	
BOARD NO.	2513757	REV	B	DATE	16 AUG 2014
		PRJ#		SH	11 OF 14



CUSTOMER NAME		TEXAS INSTRUMENTS		ASSEMBLY BOT 2 of 2	
BOARD NAME		HIRES SINGLE DLPC900		DESCRIPTION Silkscreen - Bottom Side	
BOARD NO.	2513757	REV	B	DATE	16 AUG 2014
PRJ#		SH	12	OF	14